

Abstract of Disclosure

The claimed invention discloses a chip adhesive that is adhered to a stacked packaging structure between two adjacent chips. The chip adhesive
5 includes a plurality of stuff particles to keep the chip adhesive with a predetermined thickness through suitably controlling type and quantity of the stuff particle. Two adjacent chips can be adhered together with a specific gap. The cost of dummy die can be saved and the space for wiring bonding can be retained. The chips of the stacked packaging structure, moreover, can be
10 packaged with a faced-up type to reduce the cost of applying flip chip type or WBGA type.